

**AMENDMENT TO THE SPECIFICATION**

Please replace the paragraph within the substitute specification filed on July 3, 2002 beginning at page 5, line 18, with the following rewritten paragraph.

-- Preferred embodiments of this invention are to be described in detail with reference to the drawings. Figs. 1A and 1B are an example of schematic step charts illustrating a method of manufacturing a thin film semiconductor device according to this invention. At first, as shown in Fig. 1A, a manufacturing substrate 20 having characteristics durable to the process for forming a thin film transistor and a product substrate 1 having characteristics suitable to direct mounting of a thin film transistor are prepared. In the preparatory step, a manufacturing substrate 20, for example, made of an inorganic material, such as glass, and a product substrate 1 made of an organic material, such as plastic, are prepared. In this embodiment, non-alkali glass is used as the manufacturing substrate 20. The heat resistance of the non-alkali glass is about 500 °C. The standard thickness for the manufacturing substrate 20 is, for example, 0.7 mm. If it is reduced to 0.5 mm, there is no particular problem in view of the manufacturing process. In this embodiment, non-alkali glass is used but, instead, metal plate, such as of stainless steel, plastic plate, quartz and the like, can be also be used.

On the other hand, for the ~~manufacturing-product~~ substrate 1, it is necessary to have a heat resistance capable of withstanding the processing temperature of a thin film transistor, and it is necessary that the product substrate 1 is thinner and lighter compared with the manufacturing substrate 20. In this embodiment, a plastic material is used with a thickness from about 0.1 mm to 0.5 mm. Particularly, polyether sulfone resin (PES), polyethylene terephthalate resin or ARTON resin of excellent heat resistance is used. The polyether sulfone resin has a heat resistance as high as about 250 °C. The plastic film used for the ~~manufacturing-product~~ substrate 1 may be a single layer and, depending on the case, has a laminate structure. Particularly, when this is used for a reflection type display and not a transmission type display, a metal plate can be used instead of the plastic material. However, when the metal plate is used for the product substrate 1, the surface has

to be insulated. For example, when an aluminum plate is used for the product substrate 1, the surface has to be previously covered with alumina. --